

The ISA-200 is designed for inert gas ion beam etching as well as for reactive ion beam etching. He-backside cooling, work piece heating, SIMS for end point detection, CAIBE, interface for clean room, beam monitoring with Faraday cup array and other helpful features are available. A second ion source can be attached to combine the etching process with an ion beam assisted coating process via up to four sputter targets.



## TECHNICAL DATA

### WORK PIECE DATA

Diameter:	Ø200 mm (Ø8")
Thickness:	50 mm (2")
Weight:	max. 2 kg (4.4 lbs)
Contact angle:	0 – 180°
Rotation speed:	0 – 10 rpm
Shape:	plane, spherical, aspherical, freeform

### SINGLE LOAD LOCK SYSTEM

Loading time:	< 2min.
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### AXIS SYSTEM

Type: 200	X, A, B
Travel:	X = 300 mm A = 0 – 120° B = 360°

### DIMENSIONS

Weight:	2200 kg (4840 lbs)
WxHxD:	2.55 m x 2.48 m x 2.25 m (100" x 97" x 89")
Footprint:	3.5 m x 3 m (138" x 118")

# ISA200

